

## **WEICAI LCD/LED Bonding Machine**

## CR-815SH-19M







## Here are the specifications for the CR-815SH-19M COF Bonding Machine in points

**Bonding Type: COF (Chip on Film)** 

Application: Ideal for LCD, LED, and OLED screen repairs

Precision: High-precision bonding for accurate connections between flexible circuits and display

panels

Automation: Automated alignment for consistent and reliable results

Temperature Control: Advanced temperature regulation for optimal bonding conditions

Pressure Control: Adjustable pressure settings for various screen types

User Interface: Intuitive and user-friendly for easy operation

Speed: Efficient bonding process to increase productivity

Compatibility: Supports a wide range of screen sizes and types

Build Quality: Durable construction for long-lasting performance in professional environments.

| Device Model                               | CR-815SH-19M  |
|--|---|
| Device Name                                | Hot Press Machine   |
| Device Description                         | Screen repair equipment, LCD repair equipment, COF/TAB bonding equipment, etc.  |
| Device Uses                                | This product is used in a variety of FPC, COF, TAB and LCD Panel and PCB combination bonding, is reflected in a variety of sizes LCD vertical, horizontal, vertical band, horizontal belt, black belt, black, colored thread, ribbon, multiline, black, black and white, vertical half display,horizontal half breakdown maintenance. |
| Device Features                            | Single head ,single pneumatic device, single temperature control.   |
|  | Multi-speed pulse source design to meet the power requirements of diversified product pressure.   |
| Applicable LCD panel specifications        | 15"-65"(Platform expandable)  |
| Applicable LCD panel<br>Thickness          | 0.3MM-1.1MM[Single glass]   |
| Panel Type                                 | TFT   |
| Bonding IC Number                          | One/PANEL   |
| Bonding Direction                          | X or Y Unidirection   |
| Bonding Head Size                          | Replaceable blade according to IC specifications (The original machine is equipped (50*1.4*10mm).   |
| Production Beat                            | TAB, 100pcs/H   |
| Bonding Accuracy                           | ±1.5μm (support 4K)   |
| Highest Positioning Accuracy<br>Setting    | ±0.5µm  |
| Equipment Requirements<br>Work Environment | Clean, Dust Free, Clean Room  |
| Supply Pressure                            | 0.1~0.7Mpa Dry air source   |
| Power Supply                               | AC 220V±10%,50HZ,3500W  |
| Pneumatic Device                           | Air TAC Original precision cylinder   |
| Pressure System                            | Pressure system parallel bar structure eliminates the weight of the indenter,pressure minimum accuracy can up to 0.1 KG,pressure components are using SMC precision components.   |
| Heating Method                             | Pulse (rapid heating/cooling and auxiliary cooling).<br>Brand:Omron   |

| Temperature Control System             | Brand:Omron   |
|--|---|
|  | Adjustable temperature rise curve with high precision PID auto-tuning.                  |
|  | The peak temperature : within +/-1degrees Celsius.                                      |
|  | Room temperature time to 180 degrees the response time within 2-3 seconds.              |
| Hot Pressing Head                      | Material: Titanium alloy  |
|  | Metal Properties:SUS440C  |
|  | Origin: United States   |
|  | Plane Precision (hot pressing surface) :0.001mm   |
|  | Plane thickness 0.5 (keep 3 times grinding).  |
| Thermocouple Type                      | K Type Original US OMEGA wire   |
| Industrial control unit /<br>Programme | Display Control   |
| Touch Unit                             | Display Control: Touch sc <mark>reen.</mark>  |
| Rated Voltage                          | AC 180-220V   |
| Peak Power                             | 400-1100W (can support 68X1.4X10 wide bonding head).                                    |
| Maximum Power                          | 1100W TECHNOARTS  |
| Actual Power                           | 580W  |
| Body Size                              | 1800X1200x1520mm(L*W*H)   |
| Net Weight of Equipment                | 430KG   |
| Number of Packages                     | 2   |
| Equipment Packaging                    | Wooden boxes, non-logs (material is glued board, no fumigation is required for export). |
| Package Size and Gross<br>Weight       | □920X920X1660mm (L*W*H) 320KG   |
|  | □1920X520X960mm (L*W*H) 110KG   |

| Image Unit               | COF Counterpoint: Down counterpoint (Optical Path: Lens> Quartz> ITO Electrode> COF) |  |  |
|--------------------------|--|--|--|
|                          | PCB alignment:None (optional installation).  |  |  |
|                          | Number of lens: 2  |  |  |
|                          | Microscope: 200-300 continuous zoom  |  |  |
|                          | COF Display screen: 19 inches HD   |  |  |
|                          | PCB Front Camera:None (optional installation).                                       |  |  |
|                          | PCB Alignment Display: switchable  |  |  |
| COF Trimming Unit        | Origin: China  |  |  |
|                          | Rail Type: U-rail  |  |  |
|                          | Accuracy:0.01  |  |  |
|                          | Adjustable Direction:X/Y/R   |  |  |
|                          | R stroke: coarse adjustment 360 degrees, fine adjustment +/- 5 degrees               |  |  |
| COF Fixture              | COF Mechanical clamping type ,Z-direction tilt radius micrometer finetuning.         |  |  |
| Lens Spinner Unit        | Control Mode: X / Y / Z micrometer control   |  |  |
|                          | Focus Adjustment: Manually adjust the focus  |  |  |
| Silicone / Teflon        | Manual Switching position  |  |  |
| LCD Stage (Platform)     | Manual Slide Movement  |  |  |
| Bonding Head Alignment   | The cylinder can be set to stop in any position in the upper and lower directions.   |  |  |
| Control Method           | Touch Screen + button operation  |  |  |
| Parameter setting        | Can store multiple sets of hot pressing parameters as needed                         |  |  |
| The following picture is | The following picture is the device after packaged.                                  |  |  |



